

MYNNews

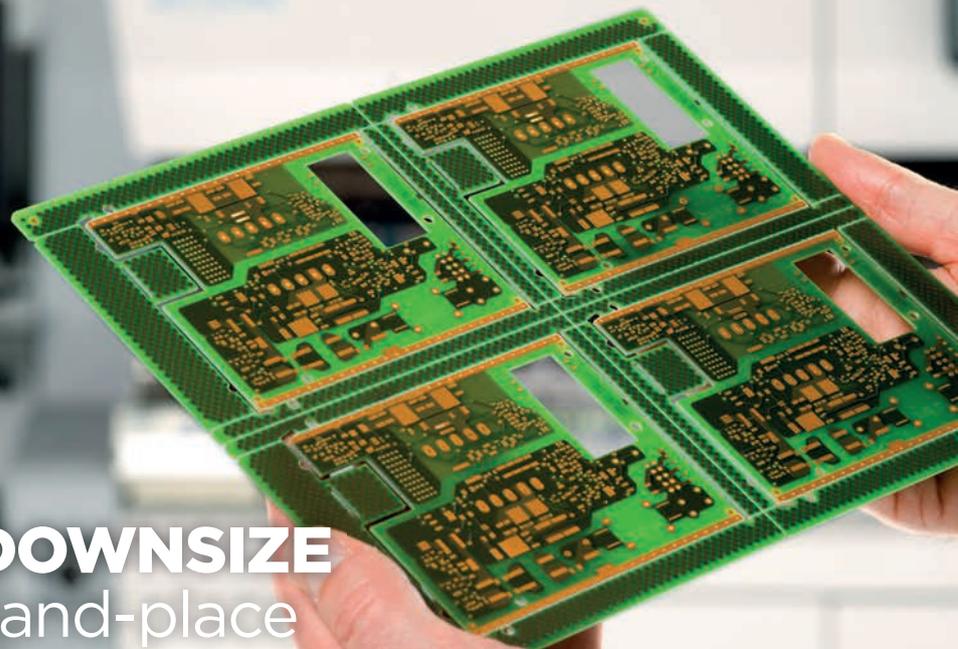
A magazine from Mycronic

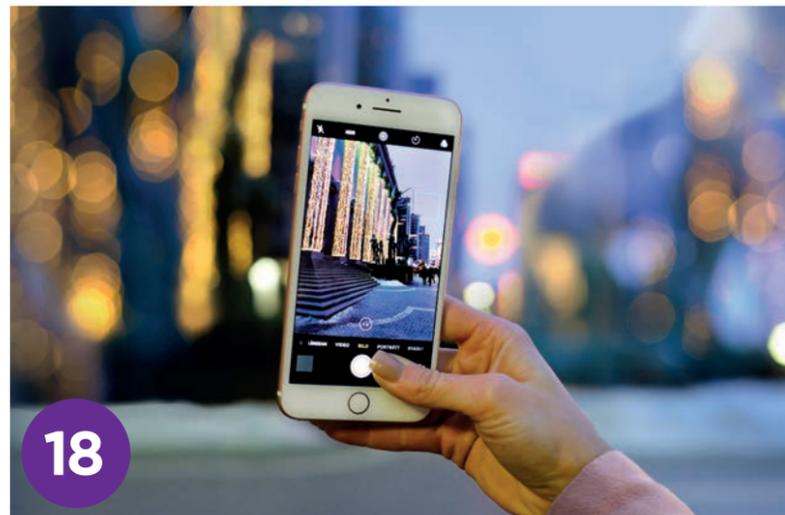
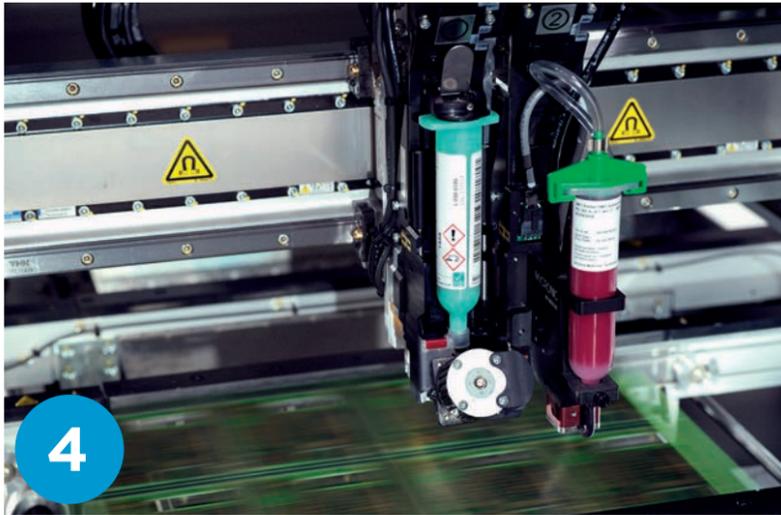
2017.01

MORE SPEED LESS SPACE

UPGRADE AND DOWNSIZE
a new era of pick-and-place
productivity

SMART DISPENSING
made simple





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ELECTRONICS ASSEMBLY IS ENTERING A NEW ERA. An era of increasingly complex package technologies, deeply integrated production lines and closed-loop data analytics. Our factories are becoming more intelligent, more productive and more versatile. And our organizations are continuously demanding new areas of expertise. Like our customers, at Mycronic, we are determined to be a driving force in this transformation. And today I can confidently say that we are very well equipped to handle whatever challenges tomorrow may bring.

Over just the past year, Mycronic expanded its offering for assembly solutions to encompass far more capabilities and applications than ever before. At Productronica 2017, we could proudly present for the first time our complete range solutions, including the new MYPro series, the MYSmart series and the recently acquired Vi TECHNOLOGY 3D visual inspection systems. The customer response was overwhelming. Not only was it our best attended event in years, but it also led to more than the double the number of customer requests.

Our customers excitement had much to do with our new platforms. There was the fully software-driven MYPro automation line, with its minimal footprint and high-productivity jet printing and pick-and-place capabilities. There was the launch of MYSmart series, an exceptionally cost-effective portfolio of solutions for nearly any dispensing or conformal coating application. And in yet another new area for Mycronic, we also showcased with Vi TECHNOLOGY several of the world's most advanced 3D visual inspection systems.

But more than just the individual modalities in an in-line set-up, it is the sum of this new combined portfolio that I believe points to a bright future. With the addition of visual inspection systems, we will offer Mycronic customers access to more integrated data analytics across these modalities. Although we are committed to standardized and open interfaces for mixed environments, we aim to enhance our offering of integrated solutions to let our customers take advantage of closed-loop data analytics which enable – for example – real-time tolerance refinements and lead to further productivity gains. In the not-too-distant future, this enhanced intelligence will open up the possibility for manufacturers to come close to a goal that was once unimaginable: the zero-defect production line.

As someone with a long background in factory automation, this is a thrilling prospect. With all of the new talent and expertise gained from our recent acquisitions, we now have a deeper and broader understanding of the production challenges you face as a Mycronic customer. I look forward to bringing all of this knowledge together to better serve your needs. And I hope you will continue to join us in our efforts to create the future of electronics.

// Thomas Stetter
Senior Vice President Assembly Solutions

MYCRONIC

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Worldwide events calendar

Mycronic will be represented at the following trade fairs:

January 2018

Internecon Japan
Dates: January 17–19
Location: Tokyo, Japan

February 2018

APEX
Dates: February 27–March 1
Location: San Diego, USA

March 2018

Productronica China
Dates: March 14–16
Location: Shanghai, China

April 2018

Nepcon China
Dates: April 24–26
Location: Shanghai, China

June 2018

SMT/Hybrid/Packaging
Dates: June 5–7
Location: Nürnberg, Germany

August 2018

NEPCON South China
Dates: August 28–30
Location: Shenzhen, China

More speed, less space – meet the new MY700™

TEXT: GRANT BALDRIDGE PHOTO: MAGNUS ELGQVIST

A new industry standard is here. With throughputs high enough for the largest volume producers, the new compact, dual-head MY700 removes all barriers to full-scale automated jet printing and assembly fluid dispensing.



IN JUST OVER A DECADE, solder paste jet printing and assembly fluid dispensing have come a long way. What was initially a small-batch platform for prototyping and early adopters is now a mature solution that's essential to intelligent production for hundreds of industrial, medical and commercial electronics assembly manufacturers worldwide.

The MY700 takes this success into the next generation with a substantially smaller footprint, significantly faster cycle times and multiple process steps – all in a single platform.

Three high-speed models

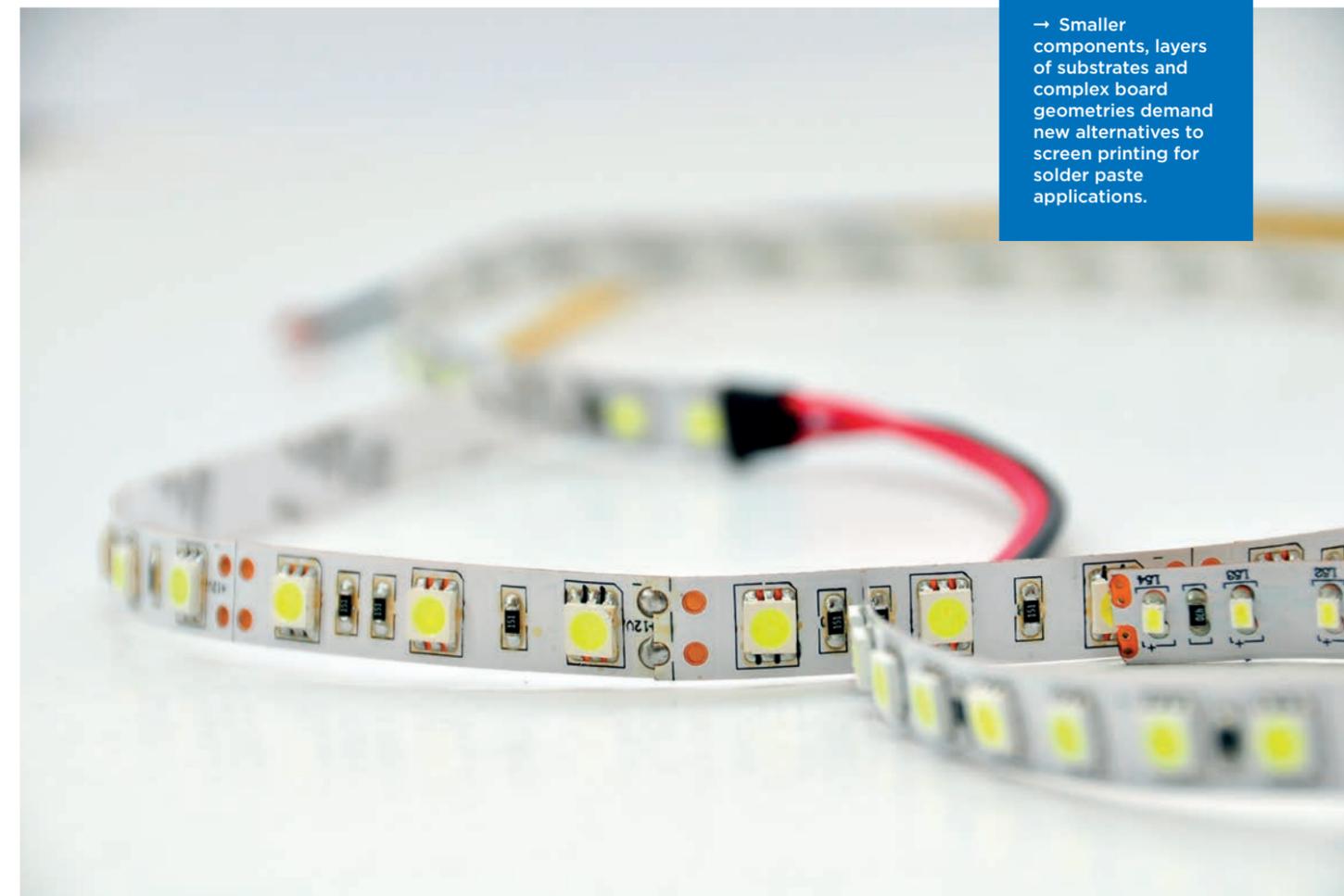
The versatile new MY700 is now available in three different models, each with its own unique set of capabilities: the MY700JD

Jet Dispenser, the MY700JP Jet Printer, and the MY700JX Jet Printer and Dispenser.

Reduced non-jetting time

One of the key advantages of the MY700 is its new dual-head format. In the MY700JP, this improves flexibility and throughput by making it possible to jet both large and small solder paste dots at speeds of more than one million dots per hour. All thanks to Mycronic's unique ejectors that can now be combined in one machine to cover a wide range of dot sizes.

In the MY700JX, the dual heads allow users to combine solder paste jet printing with assembly fluid jet dispensing, enabling a broad range of process steps in just one machine. "The MY700JX opens up a lot of interesting new possibilities," explains



→ Smaller components, layers of substrates and complex board geometries demand new alternatives to screen printing for solder paste applications.

Håkan Sandell, Chief Architect at Mycronic, "like combining complex pin-in-paste applications with highly efficient SMA or glue dispensing."

Faster loading and fiducials on-the-fly

An optional dual-lane configuration serves to further improve cycle times. By ensuring efficient in-line board handling, it virtually eliminates board transfer times.

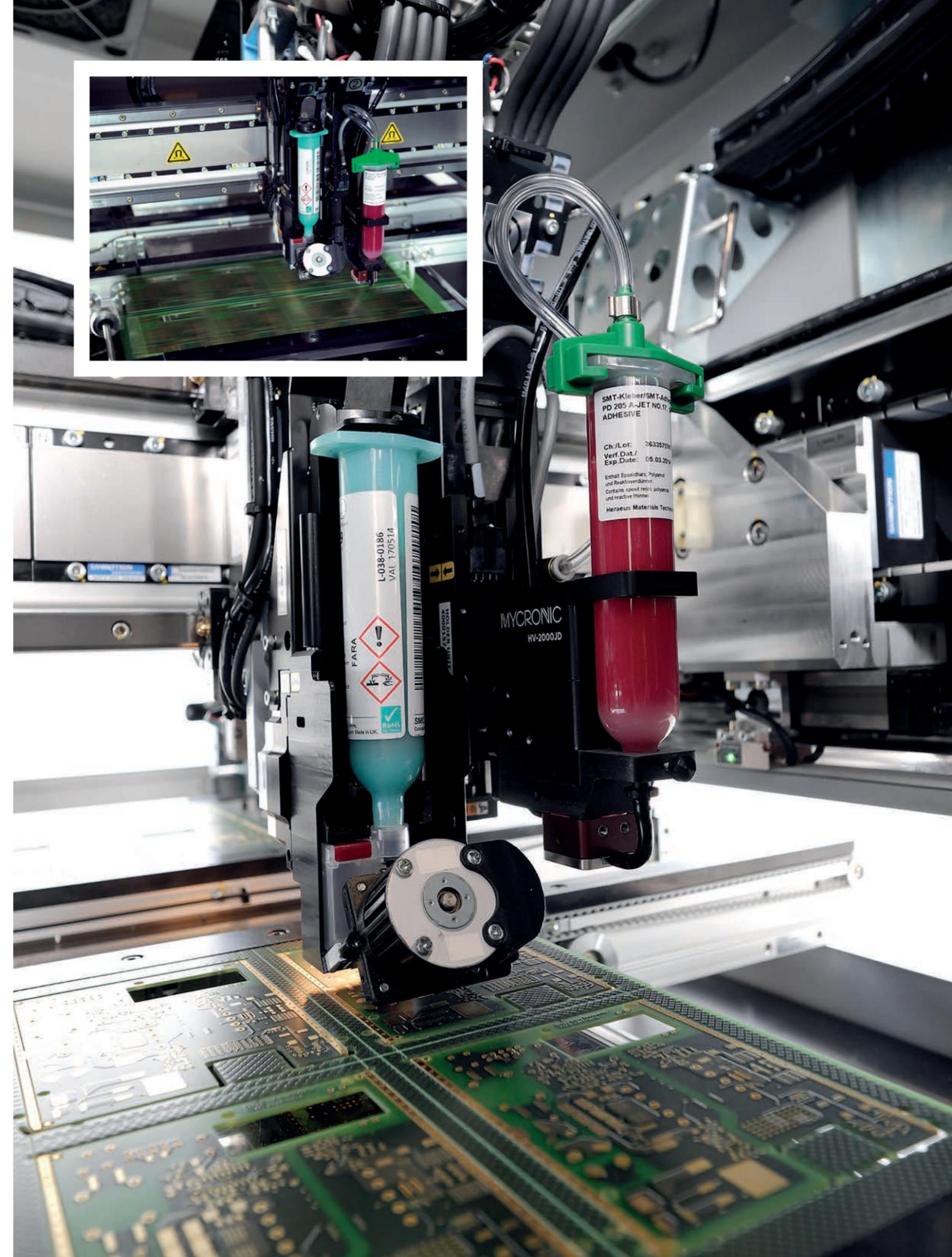
Fiducial recognition is also much faster, thanks to a state-of-the-art vision and laser height measurement system. This enables

on-the-fly recognition of fiducials, together with automatic board stretch and warpage compensation, which help to ensure superior throughput with higher yield.

40% smaller footprint

To free up valuable floor space, the MY700 has been reduced to a 40% smaller total footprint than previous machine generations. The compact design is accessible from both front and rear, and measures just one-and-a-half square meters, making it possible to fit two machines into nearly the same line length as a single MY600.

The compact design is accessible from both front and rear, and measures just one-and-a-half square meters.





The MY700 Jet Printer and Jet Dispenser



Dual lanes. Dual heads. Twice the possibilities.



MY700 - Double your capabilities in jet printing and dispensing

The future of mixed production belongs to those who can handle any solder paste or fluid deposit with absolute precision and unmatched speed. Part of the new MYPro series, the MY700 Jet Printer and Jet Dispenser combines solder paste jet printing with jet dispensing of adhesives, UV materials, epoxies and more - with micrometer precision and at speeds of more than one million dots per hour. The unique dual-head, dual-lane design does it all within the same compact machine and process step, meaning there's virtually no board, package or component you can't handle. Whatever your ambitions, the future is already here. In fact, it's just in time.

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“No other assembly solution brings together this range of process steps into one end-to-end, software-driven production line.”

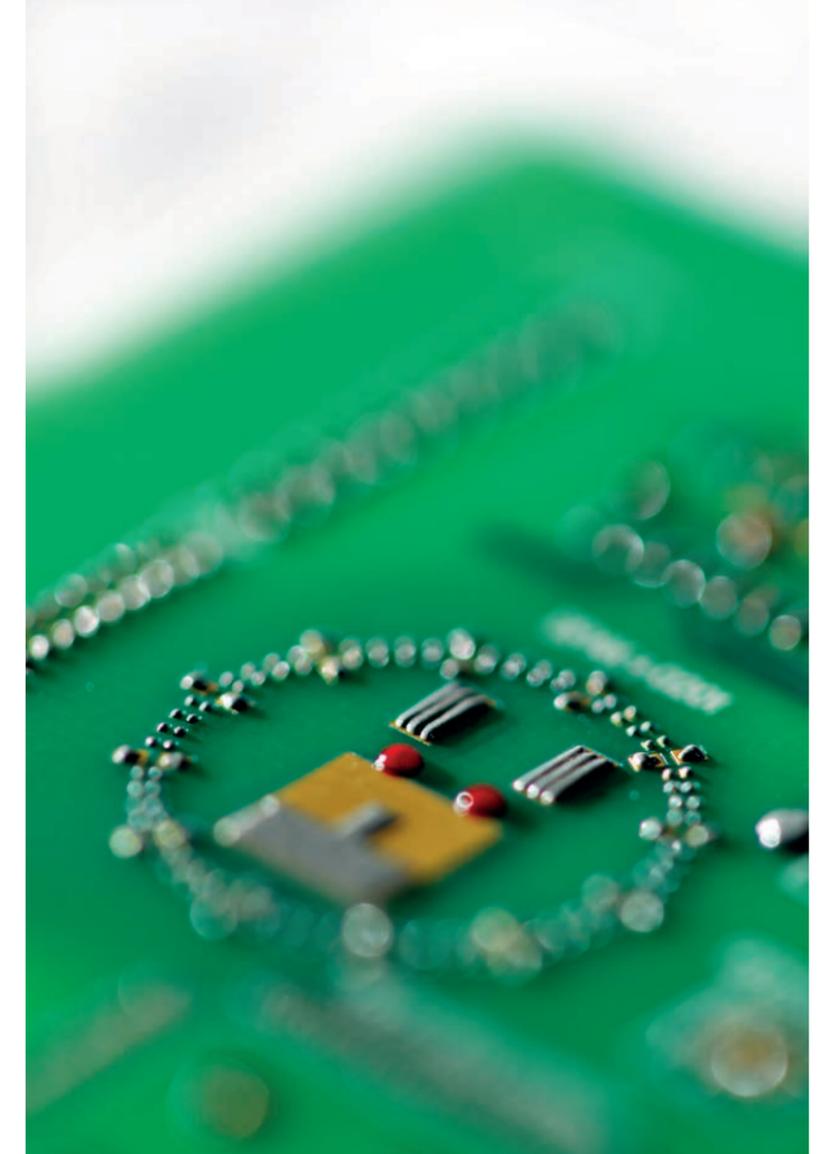
VIKTOR OLSSON
PRODUCT MANAGER

The evolution continues

In terms of speed, the MY700 marks a significant step forward for software-controlled jetting of solder paste and assembly fluids.

“Our aim was to bring together all the unique capabilities of the MY600, which already has the industry’s most advanced motion system, while doing everything possible to eliminate non-jetting time,” says Viktor Olsson, Product Manager Jet Printing. “For producers of larger boards, a broader range of dot sizes is key. For those assembling smaller modules or a lot of pre-populated boards, fiducial scanning and board loading times are critical. The MY700 removes these bottlenecks almost completely.”

Viktor Olsson is confident that the new platform will continue to build on the growing popularity of its predecessors. An upgraded offline programming software is an integral part of this development, making it possible for the system to recognize and optimize two or more MY700s as a single unit. Thanks to the machine’s reduced footprint, this modular concept makes combining multiple units into one high-throughput cell an increasingly attractive option, particularly for high-volume manufacturers.



Experience the new MYPro series

As part of the new MYPro series production line, the MY700 provides a seamless complement to the new MY300 pick-and-place solution. Together they form a stencil-free production line capable of fully automated changeovers down to batch size one.

“This is a one-of-a-kind production concept within our industry,” explains Viktor Olsson. “No other assembly solution brings together this range of process steps into one end-to-end, software-driven production line.” //

Upgrade and downsize

– MY300™ ushers in a new era of pick-and-place productivity

TEXT: GRANT BALDRIDGE PHOTO: MAGNUS ELGQVIST

Three years ago, Mycronic engineers from a broad range of disciplines assembled to address a key question: “How can we better equip manufacturers for the challenges of the coming decade,” they asked, “while maintaining the flexibility Mycronic is known for?” Their answer was a powerful, compact and productive new pick-and-place platform: the MYPro series MY300.



The MY300 accommodates up to 224 feeder positions within a 40% smaller total footprint than its predecessor.



IT ALL BEGAN WITH A SIMPLE INSIGHT. For years, Mycronic pick-and-place solutions had enabled the world’s most demanding high-mix manufacturers to overcome extremely complex production challenges. Varying batch sizes, microscopic components, challenging applications and fast-changing material flows were the norm. And the need for intelligent, flexible production solutions was a given.

All of these trends, the Mycronic team understood, were rapidly accelerating across the industry, with miniaturized components, overcrowded factories and expanding product mixes causing costly productivity losses for manufacturers of all sizes.

“We realized it was time for a new platform,” says Per Carlqvist, Lead Architect for the MY300 product development team, “one that would inherit the best of the MY200, while packing more capacity and capabilities into less space.”

A new level of space productivity

For those first encountering the recently launched MY300, the most dramatic change is the machine’s size. The MY300 accommodates up to 224 feeder positions – but within a 40% smaller total footprint than its predecessor.

For users of single machines, this opens up valuable assembly line space for additional process steps. For others, it means that two MY300s can be used to double feeder capacity in just slightly more space than a single MY200, while improved software recognizes and optimizes the two machines as a single unit. The reduced machine depth also makes the platform more user-friendly, providing improved visibility and ergonomics, as well as easy access for all types of maintenance work.

State-of-the-art vision systems

Another key challenge for today's manufacturers is to ensure accurate fiducial registration and precise positioning for increasingly miniaturized components. The MY300 answers this need with a new high-resolution linescan vision system. With 4k resolution, it can center components as small as 0.15mm in pitch, or down to 0.25mm pitch for the 2k system.

At the same time, the previously analog frame grabber board has been replaced with a more robust data interface that automatically imports high-resolution images directly into the control system. The result is a faster,

more accurate and more cost-effective vision system capable of extremely precise on-the-fly positioning and inspection for any type of miniaturized or specialized component.

Improved real speeds

In addition to upgrading and downsizing the platform, the MY300 team aimed to significantly reduce every possible productivity gap – from board loading time and fiducial scanning to component inspection and electrical verification. Instead of focusing on top machine speed, "which is an optimum that almost never happens in

reality," says Carlqvist, "we made a number of improvements to enhance real speed – the actual speed under typical conditions."

Reduced board loading times

One such area of improvement is board loading time. With fully automated board train functionality, the MY300 substantially increases throughput by simultaneously loading and unloading multiple boards. This is especially advantageous for smaller boards. Processing several of these in one cycle will substantially reduce board loading times and nozzle changes.

Multiple board layouts can also be loaded in sequence, thanks to an advanced Autowidth function that automatically scans and adjusts the conveyor according to board width. "Even with external conveyors, the system recognizes a change between one panel size and another, and automatically prepares conveyor width," explains Carlqvist.

Faster tool changes, enhanced verification

Tool banks, previously located on the internal conveyor, have been relocated on the MY300 to the new Utility Wagons. This allows tool changes to take place



MY300_{DX}

With fully automated board train functionality, the MY300 substantially increases throughput by simultaneously loading and unloading multiple boards.



The MY300 pick-and-place



Shrink your footprint. Grow your business.



Faster. Smaller. Smarter. Introducing the new MY300.

The future of high-mix production belongs to those who can get more jobs done in less space. Switch effortlessly from full volume to batch size one. And handle a wider range of components with uncompromising production quality, total stock accuracy and complete traceability. Part of the new MYPro series, the MY300 pick-and-place delivers higher levels of precision and flexibility in a faster, smaller and smarter format. So you can efficiently handle any job, board or component that tomorrow may bring. Whatever your ambitions, the future is already here. In fact, it's just in time.

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while the other head is mounting, which further eliminates unnecessary waiting times, particularly on the MY300DX. The reconfiguration also enables electrical verification to be performed directly on the utility wagon's test surface. Using redundant test patterns, it helps to reduce wear on the contact area while allowing testing of new package types, thus guaranteeing quality and eliminating time-consuming rework.

Welcome to the next generation

Put together, these comprehensive improvements amount to a new era of pick-and-place productivity. One that builds on the strengths of the MY200, but in a smaller, smarter and more robust format.

By ensuring higher real speeds and handling more advanced components within a

smaller footprint, the new pick-and-place solution is already helping to future-proof a number of production facilities worldwide. Among them are several former MY300 beta customers, including two higher-volume producers and one highly demanding high-mix manufacturer.

"The MY300 has met all of the technical goals we set out to fulfill," says Mattias Jonsson, Product Manager for the MY300 product portfolio. "This is a clear step forward for the industry."

The MY300, which together with the new MY700 Jet Printer and Dispenser marks the beginning of the new MYPro series product lineup, is available in three different models: the MY300DX, MY300SX and MY300LX. //

→ The MYPro assembly line together with intelligent component storage.



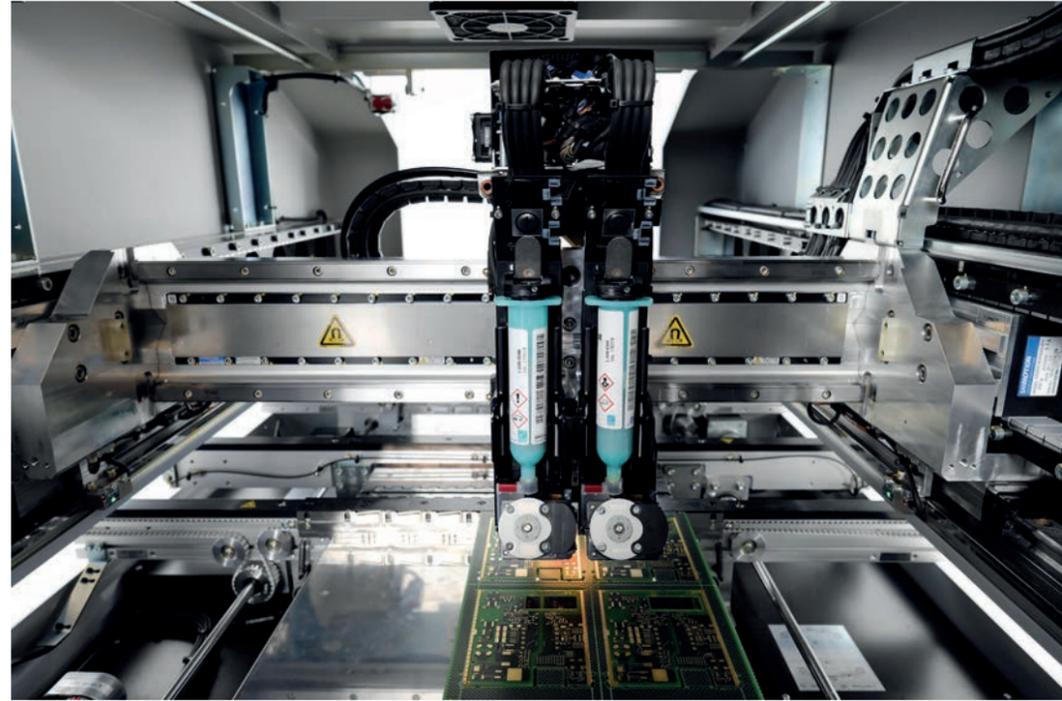


PHOTO: MAGNUS ELGOVIST

New software release – TPSys/MYCenter 4.1

MYCRONIC'S LATEST PICK-AND-PLACE SYSTEM release includes more than 50 improvements and new functions in material handling, NPI, vision programming, line control and process management. Here are just a few of them:

- ODB++ import wizard - MYCenter 4.1 can import native ODB++ files and generate both PCB data and gerber background in one go.
- New component wizard in 4.1 - it's substantially easier to create new components and link them to a suitable package. The new wizard will search the entire package library and match the lead geometry to the gerber land pattern.
- Reference image vision teaching - TPSys 4.1 includes a new vision teaching method called Reference Image. The new method is primarily intended for electromechanical or odd-shaped components, and is very robust in relation to variations in mechanical and optical properties.
- Management data provider - A new SQL interface for management data makes it possible to easily download extensive production statistics to MS Excel or other external reporting tools. Several years of detailed production data is now easily available to process engineers and managers.

All MY9-19E, MY100, MY200 and MY300 series P&P machines can be upgraded to the new TPSys/MYCenter 4.1 SW platform. //

New full range of jet printing ejectors

MYCRONIC PRESENT a full new range of ejectors for the MY700 high-speed Jet Printer. Since the launch of the MY700 the standard AG ejector has been used for a broad range of applications. Now Mycronic have extended the range of ejectors to fully support the synergies of running dual-head configurations while covering a wider range of boards and component technologies. With the new AP ejector it is possible to achieve 215 µm dots and handle fine-pitch applications for small BGAs and 01005 components. The new AQ ejector will shoot dots up to 600 µm in diameter to handle large solder paste deposits with fewer dots. Combining two different ejectors can increase throughput by as much as 48%* compared to running a single ejector. //

EJECTOR MODEL	AP	AG	AQ
Dot diameter range	215-257 µm	330-520 µm	400-600 µm
Dot volume range	2.1-3.2 nl	5-20 nl	15-30 nl

* Depending on board layout, reference board Demo Board 16



PHOTO: MAGNUS ELGOVIST

Smart dispensing made simple

TEXT: GRANT BALDRIDGE PHOTO: AXXON AUTOMATION MAGNUS ELGQVIST

Complex 24/7 manufacturing just got a lot simpler. Whatever emerging packaging technologies, new materials or dispensing media you might encounter, dispensing and conformal coating are no longer any obstacle. The new MYSmart series offers a complete range of advanced solutions for any production environment.

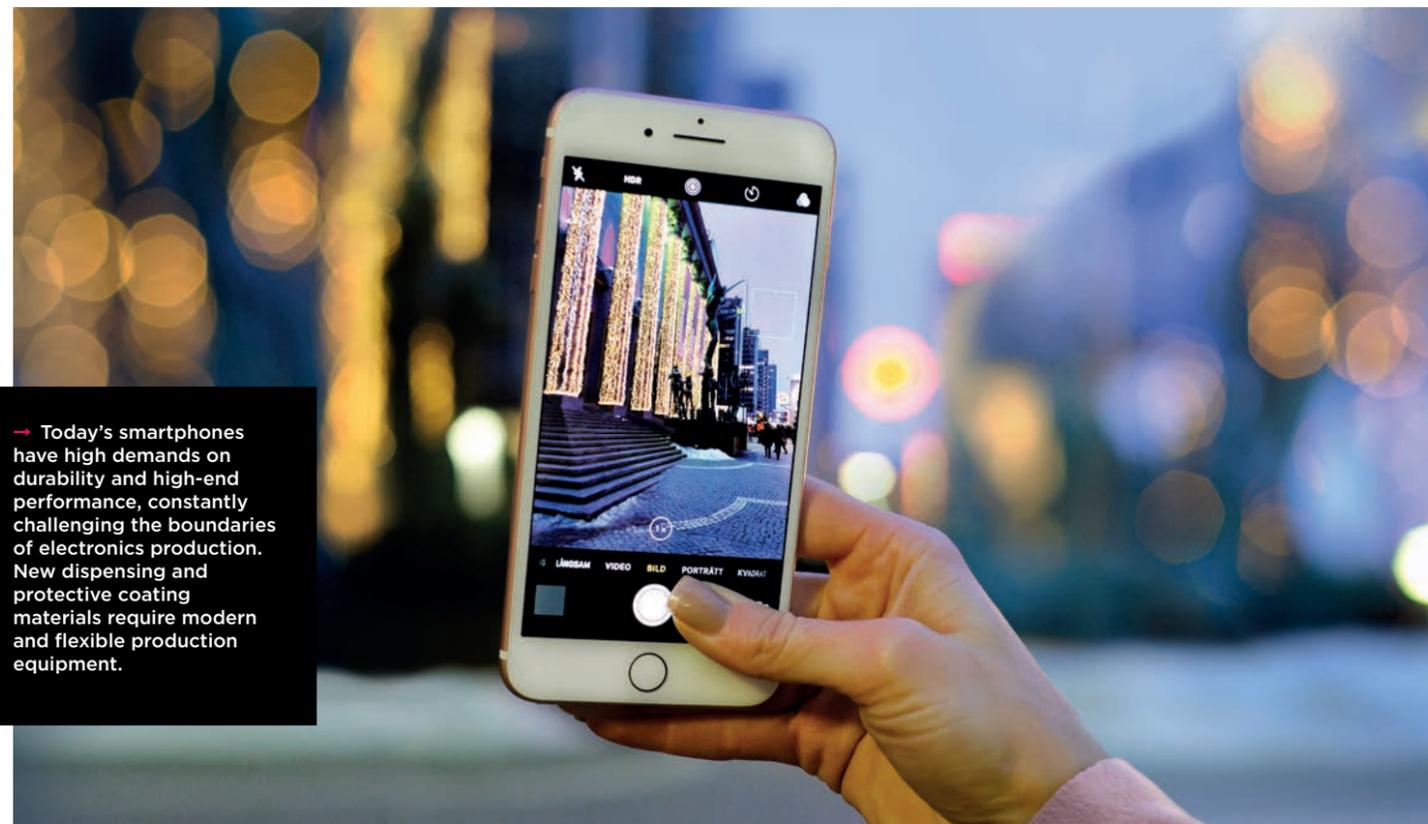
THE BIRTH OF A NEW PRODUCT FAMILY.

Back in 2016, when Mycronic acquired China's leading manufacturer of fluid control automation systems, a new global leader in dispensing was born. Axxon, whose high-end electronic assembly solutions are used by world-leading high-volume manufacturers of electronic assemblies, was a near-perfect fit in terms of technology.

"On a product level, there is virtually no overlap between Axxon's fluid control systems and Mycronic's assembly, material handling and jet printing technologies," explains Thomas Stetter, Sr VP Assembly Solutions. "They complement each other seamlessly."

As a result, Mycronic was very quickly able to address a wide range of new

Together with the MYPro series, the new MYSmart series vastly expands the capabilities of Mycronic customers to address future production challenges.



→ Today's smartphones have high demands on durability and high-end performance, constantly challenging the boundaries of electronics production. New dispensing and protective coating materials require modern and flexible production equipment.

customer needs within dispensing and conformal coating. A project team was rapidly put in place to standardize the right portfolio of Axxon technologies, with the right premium features for international customers. The result is the new MYSmart series.

Small-batch dispensing robots

Lower volume manufacturers often lack both the floorspace and throughput requirements for in-line dispensing solutions. Yet high-precision dispensing for complex PCBs and semiconductor packages remains an absolute necessity. The new MYT10 and MYT50 series of tabletop dispensing robots are designed precisely to fill this gap.

The semi-automated MYT10 series is one of the industry's most cost-effective solutions for handling odd-shaped electronic and industrial packages. It is also extremely robust and flexible for an array of testing, welding and industrial dispensing applications.

When more advanced process controls are necessary, the MYT50 series adds automation features on a par with many in-line systems. These include automated calibration and visual inspection, barcode and fiducial scanning, and z-axis laser height measurement. This compact tabletop platform performs automatic needle calibration with intelligent valve control, making it possible to handle the most complex program routines with minimal setup or stoppage times.



MYT50

IN-LINE CAPABILITIES in tabletop dispenser. The MYT50 offers functionality usually only found in an in-line system. Automated calibration, z-axis laser height measurement and inspection to name a few. //

MYD10

THE COMPACT MYD10 enables highly advanced non-contact jetting for enhanced dispensing uniformity, throughput and material utilization. These highly flexible platforms have proven themselves in semiconductor packaging applications such as underfill, silver epoxy or flux, as well as high-speed SMA, glob top or solder paste jetting for PCB assembly. //



MYC50

THE MYC50 is a high-performance conformal coating system that ensures non-stop throughput across a range of high-volume applications. Thanks to a robust frame structure and advanced motion configuration systems, it gives manufacturers the ideal combination of speed and precision for an endless variety of coating demands. //

High-volume in-line dispensers

High-volume manufacturers need to tackle an array of challenging applications at much higher throughput rates. Whether it is flux, underfill or silver epoxy for semiconductor packaging, or high-speed SMA, glob top and solder paste jetting for PCB assembly, the versatile MYD10 and MYD50 in-line platforms can do it all.

The more compact MYD10 utilizes state-of-the-art non-contact jetting to enhance dispensing uniformity, throughput and material utilization. The more powerful MYD50, with its linear motor motion control system, further boosts productivity in high-precision applications such as complex chip packaging.

“The factories currently using Axxon’s in-line dispense systems represent the absolute forefront in electronics assembly,” says Clemens Jargon, VP Global Dispensing at Mycronic. “This includes many of the highest volume smartphone, automotive and home electronics manufacturers we all recognize today. Needless to say, the MYD10 and MYD50 are based on extremely well-proven technologies in some of the world’s most demanding environments.”

Versatile conformal coating equipment

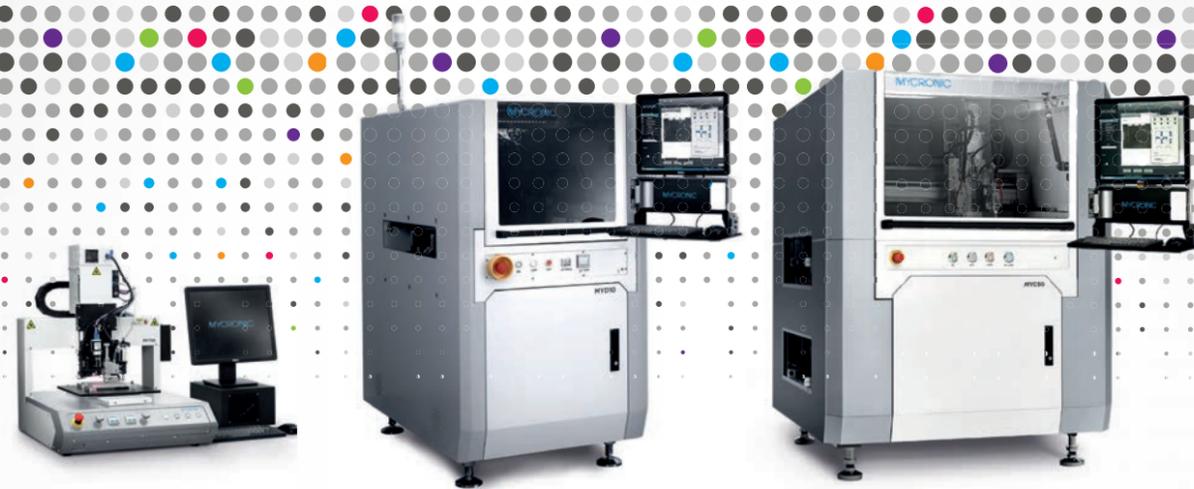
In addition to covering a vast range of dispensing applications, the MYSmart series was developed out of the recognition of the growing demand for high-precision conformal coating. As more and more products become embedded with advanced electronics, the need to precisely deposit coatings to protect these electronics from the environment continues to rise.

To solve this challenge, the MYC50 in-line conformal coating platform combines high-accuracy edge control with sophisticated feedback systems. From spray and needle coating to film coating, it covers all types of applications and materials regardless of formulation, whether they be UV, humidity or heat cured.

The combination of advanced motion control systems and flexible multi-axis movement helps to ensure non-stop throughput with precision across a range of high-volume applications. Multiple valve configurations include a triple-mode spray valve, film coating valve and needle jet valve. An easy-to-use interface makes it simple to monitor a number of process control parameters, or program automated PCB coating, multi-valve patterns and traceability via barcode scanning.



Introducing the new MYSmart series

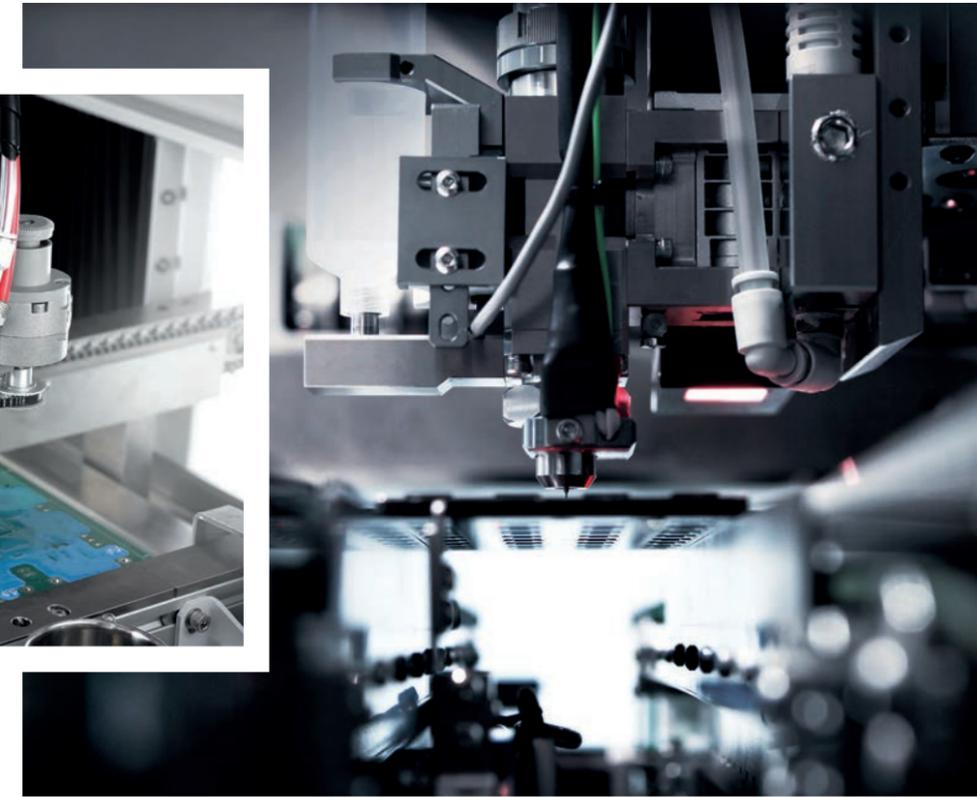
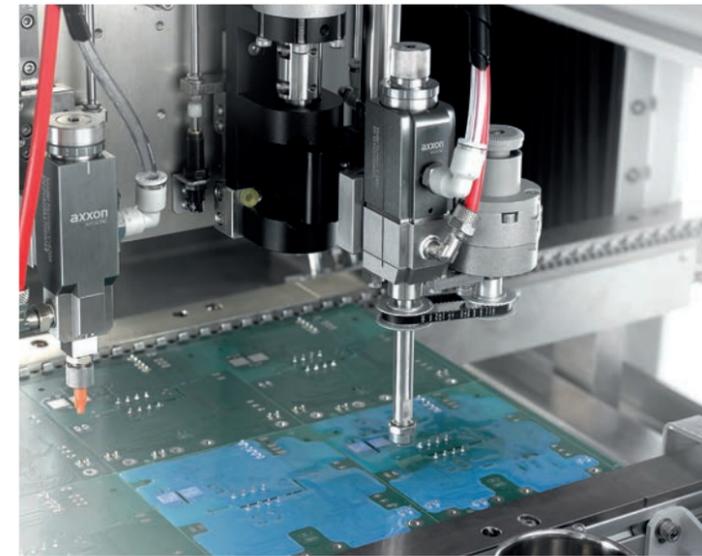


Smart dispensing made simple.

MYSmart series – enabling the future of dispensing and conformal coating

The future of electronics assembly belongs to those who can efficiently handle growing complexity, emerging package technologies and a wide range of dispensing media at ever-increasing volumes. The MYSmart series answers these rising challenges with a comprehensive range of compact tabletop dispensers and versatile in-line coating and dispensing systems. Underfill, silver epoxy or flux. High-speed SMA, glob top or solder paste. Film coating, spray coating or needle jetting. The MYSmart series handles it all with advanced standard features proven in the world's most complex, high-volume production environments. Giving you a complete selection of smarter, simpler, more accurate solutions – for whatever challenges the future brings.

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Wherever quality, consistency or limited spray settings continue to pose problems, the MYC50 can bring major improvements to nearly any production setup. For factories where conformal coating is still carried out manually – often by dipping, tape masking and spraying – the productivity and quality gains can be immense.

A leap forward for future productivity

Together with the MYPro series, the new MYSmart series vastly expands the capabilities of Mycronic customers to address future production challenges with the highest levels of reliability, precision and automation. “Thanks to a wide selection of advanced dispensing and coating equipment, we can now give customers just the right choice for their

specific production demands,” says Clemens Jargon. “Whether it’s optimizing dispense precision and volume, enabling better control of coating area and thickness, or boosting process speed, the MYSmart series really delivers unmatched production value.”

As the electronics packaging supply chain becomes increasingly complex, this value will only continue to grow. With compact smartphone technologies, advanced semiconductor packaging and robust camera modules constantly reshaping our world – and our industry – the MYSmart series represents a major step forward in maintaining high levels of productivity and precision. Whatever challenges are yet to come, one thing is certain: For Mycronic customers, there are now more production possibilities than ever before. //



Expanding our vision

TEXT: GRANT BALDRIDGE PHOTO: VI TECHNOLOGY

Following the acquisition of Vi TECHNOLOGY in October 2017, Mycronic now offers a full range of state-of-the-art automated vision inspection systems. This represents an important step towards tomorrow's intelligent SMT factory.

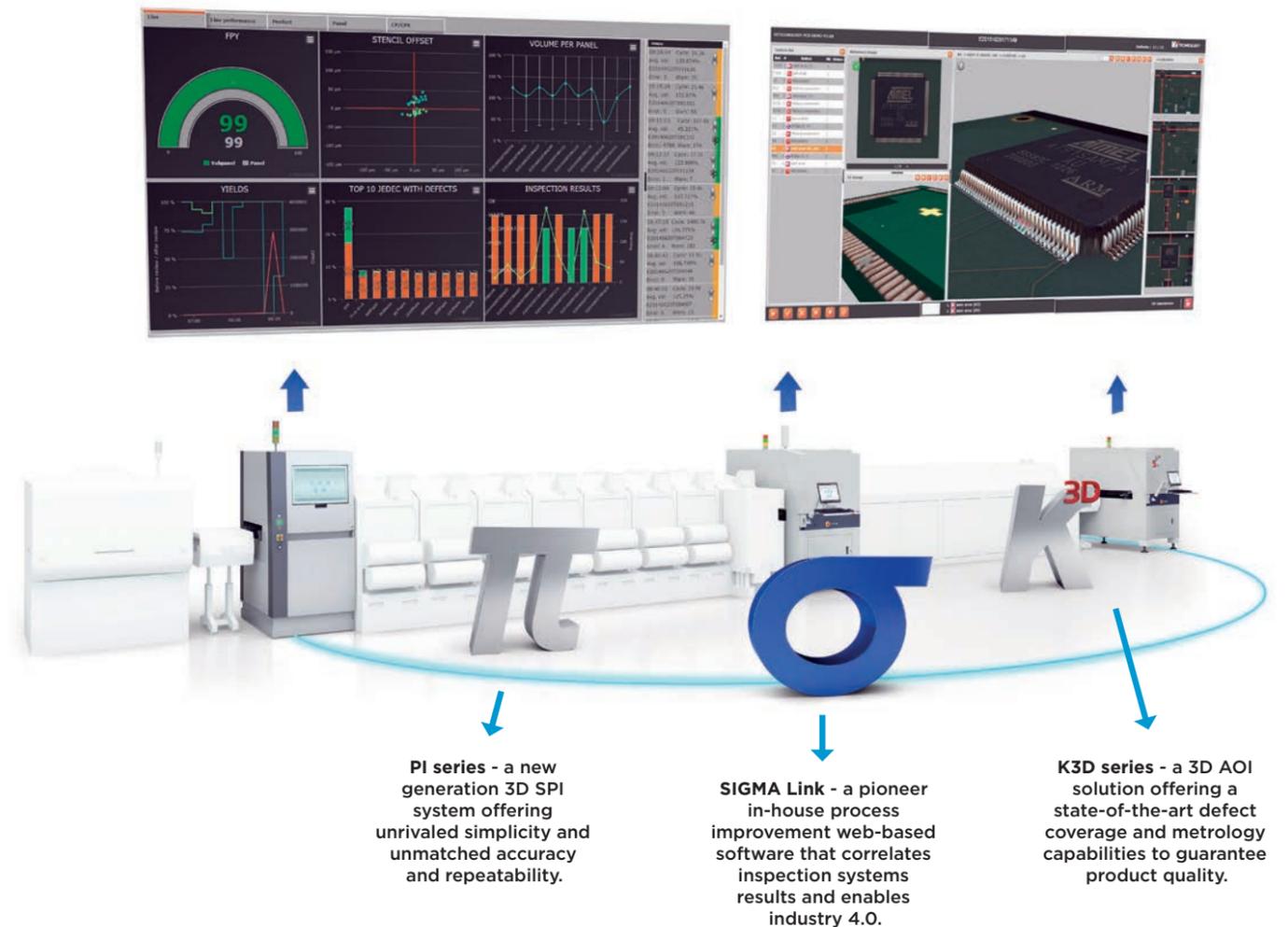
VI TECHNOLOGY, based in Grenoble, France, brings more than two decades of advanced expertise, software and inspection systems into the Mycronic family. The product portfolio encompasses an advanced process software suite SIGMA Link, K3D series of automated optical inspection machines and PI series of advanced solder paste inspection systems.

The new product portfolio of inspection systems will come as welcome news for electronics producers experiencing a need for improved automation while handling more and more miniaturized technologies. The

portfolio of 3D inspection systems from Vi TECHNOLOGY are known for their accuracy and for offering a broad range of tests for manufacturing defects, while being straightforward and cost-effective to use. Existing customers include many of the world's largest smartphone, aerospace and consumer electronics manufacturers.

"We aim to enable the zero-defect line in today's smart factory," says Olivier Pirou, General Manager at Vi TECHNOLOGY. "The software that we call SIGMA Line, which leverages 3D SPI and 3D AOI big data to optimize process tolerances and increase

A full range of automated vision inspection systems.



first-pass yield, is one thing that makes us very unique. We also revolutionized the 3D SPI space with our new PI system, which is the first fully auto-programmed system on the market. As part of Mycronic, we're excited to take the huge volumes of process data our systems produce and transform them into valuable, actionable information for customers," Pirou concludes.

Mycronic offers a complete manufacturing solution - Mycronic 4.0 - that provides customers with advanced tools that enable efficient production planning, material tracking, fast changeovers, intelligent

component storage and automatic replenishment of parts. With the acquisition of Vi TECHNOLOGY, Mycronic has gained access to advanced inspection technology and software solutions as well as leading expertise. "We will continue our efforts to develop advanced solutions based on our combined expertise. The unique combination of jet printing and inspection technology will provide new ways of optimizing manufacturing. Our customers will get a complete and integrated production line to further increase their productivity," says Thomas Stetter, Sr VP Assembly Solutions at Mycronic. //



Introducing the new MYPro series



The future of intelligent productivity.



The industry's smartest high-mix line is now more versatile than ever

The future of high-mix production belongs to those who can mount any component on any board. Handle any batch or series with zero changeover times. And jet solder paste and adhesive deposits with high-precision at record speeds. The new MYPro series combines two of the industry's most productive platforms - the MY300 and MY700 - giving you more capabilities than ever before within a 40% smaller footprint than previous generations. Simply put, it's the smartest way to boost quality and utilization across a vast range of challenging applications. Whatever your ambitions, the future is already here. In fact, it's just in time.



Agilis™ Smartbox

THE AGILIS SMARTBOX is a general purpose storage box for trays, pre-loaded feeders with 7" reels, bags with components, or any other small items that you want to store in a controlled manner. Smartboxes can be stored in the SMD Tower, or they can be stacked on top of each other on a shelf. All material stored in the Smartbox can be registered in MYCenter, or in STSys for customers running the towers without MYCenter, for tracking purposes.

The Smartbox comes with a printed barcode as standard, but it can alternatively be equipped with an electronic label, i.e. E-label. The E-label remains visible when Smartboxes are stacked, enabling MYCenter to guide the operator to the correct box when collecting material. The Smartbox is available in three different heights: 24 mm, 32mm and 44 mm. When stored inside the SMD Tower, it will occupy a 13" position. Please use the following part numbers when ordering. //





Introducing the new MYPro series

THE FUTURE
IS ALREADY
HERE.

IS YOUR
FACTORY
PREPARED?



The new MYPro series – the perfect fit for any intelligent factory

The future of high-mix production belongs to those who can mount any component on any board. Handle any batch or series with zero changeover times. And jet solder paste and adhesive deposits with high-precision at record speeds. The new MYPro series combines two of the industry's most productive platforms – the MY300 and MY700 – giving you more capabilities than ever before within a 40% smaller footprint than previous generations. Simply put, it's the smartest way to boost quality and utilization across a vast range of challenging applications.

Whatever your ambitions, the future is already here. In fact, it's just in time.

MYCRONIC

When passion meets innovation ●